



Product Change Notification

Change Notification #: 115290 - 00

Change Title: Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x8 Standard 100HFA018FS,

Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x8 Low Profile 100HFA018LS

PCN 115290-00, Product Design, Label, Product Material

Regulatory Label Update for Korea/Taiwan and Firmware Upgrade

Date of Publication: February 14, 2017

Key Characteristics of the Change:

Product Design, Label, Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: March 01, 2017

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

Affected Product Code	Product Description
100HFA018LS	Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x8 Low Profile 100HFA018LS
100HFA018FS	Intel® Omni-Path Host Fabric Interface Adapter 100 Series 1 Port PCIe x8 Standard 100HFA018FS

Overview of Changes:

Change 1: Regulatory and Compliance Certifications were successfully acquired from Korea and Taiwan. The changes include the following:

- A. The regulatory label for the product will be updated with the Korean (KC/MSIP) and Taiwan (BSMI) marks.
- B. The Read Me First document will be updated to add the Regulatory Model Numbers.
- C. The packaging label will be updated to reflect the KC labelling requirements

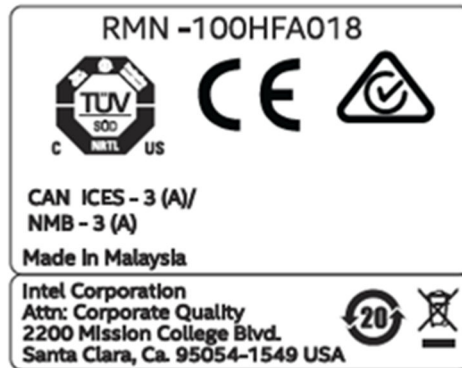
Change 2: The firmware shall be updated as follows, (reference release notes for 10.1 and 10.3):

- A. OptionROM UEFI firmware version 0x1C shall be replaced with version 1.3.0.0.0
- B. OptionROM UNDI firmware version 0x1C shall be replaced with version 1.3.0.0.0
- C. OptionROM Config version 10.1.0.0.129 shall be replaced with version 1.0.1.0
- D. TMM firmware version 10.1.0.0.101 shall be replaced with version 10.2.1.0.3

Product Material Change Details:

Change 1A: Regulatory Label showing the addition of the Korean and Taiwanese marks.

Before:



After:



Change 1B: Regulatory change showing the addition of the Regulatory Model Numbers to the Read Me First Document

Before:

Safety and Compliance
Regulatory Compliance Statements

Federal Communications Commission (FCC) Class A Statement

After:

Safety and Compliance
Regulatory Compliance Statements
Regulatory Model Numbers: 100HFA016, 100HFA018,
100HFA026

Federal Communications Commission (FCC) Class A Statement

Change 1C: Package Label change to accommodate the Korean Regulatory requirements.

Before:



After:

The following data will be added to the existing package label for Korean requirements:

1. KC Mark
2. Korean Registration Number: MSIP-REM-CPU-100HFA026
3. Equipment Name: Intel Omni-Path Host Fabric Interface Adapter
4. Regulatory Model Number: 100HFA018
5. Applicant: Intel Corporation
6. Manufacturer: Flextronics Technology

The following data will be added to the existing package label for European Union requirements:

1. CE Mark
2. Intel European Address

Similar to:



Change 2: The firmware shall be updated as follows:

- A. OptionROM UEFI firmware version 0x1C shall be replaced with version 1.3.0.0.0
- B. OptionROM UNDI firmware version 0x1C shall be replaced with version 1.3.0.0.0
- C. OptionROM Config file version 10.1.0.0.129 shall be replaced with version 1.0.1.0
- D. TMM firmware version 10.1.0.0.101 shall be replaced with version 10.2.1.0.3

Customer Impact of Change and Recommended Action:

Intel is not recommending additional qualification of these changes by customers.

There is no change to the adapter Intel Material Master (MM) numbers.

Please contact your local Intel Field Sales Representative if you have any questions about this change.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change MM# Rev	Post Change MM# Rev	Pre Change TA	Post Change TA	Pre Change AS	Post Change AS
100HFA018FS	945672	02	03	J31082-002	J31082-003	J31081-002	J31081-003
100HFA018LS	945670	09	10	J12508-012	J12508-013	J12507-012	J12507-013

PCN Revision History:

Date of Revision:

February 14, 2017

Revision Number:

00

Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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